APPLICA	BLE STAN	DARD									
Operating temperature		range	-55 °C to 125 °C (n	ote 6)	Storage temperature range			-10°C TO 60°C (Packed condition)			
RATING	Voltage		humid		humidi	idity range		Re	Relative humidity 90 % MAX (Not de		
	Current	0.50 A				Applicable cable t=0.33±0.03mm, Gold properties (Ground plate : Tin plate)				_	
			SPEC	IFICA	10IT	NS					
	ГЕМ		TEST METHOD				RI	EQU	IREMENTS	QT	АТ
	RUCTION	_				1					
General examination		Visually and by measuring instrument.				According to drawing. (note 1)			×	×	
Marking			d visually.			(Hote	1)			×	×
	ICAL CHA								-		
Voltage proof		150 V AC for 1 min.				No flashover or breakdown.			×	_	
Insulation resistance		100 V DC.				500 MΩ MIN.				×	-
Contact resistance						[FPC] Initial:60 m Ω MAX、After each test:80 m Ω MAX (Including bulk resistance L=8mm)			×	-	
						[FFC] Initial:80 m Ω MAX、After each test:100 m Ω MAX (Including bulk resistance L=26mm)					
	NICAL CHA										
Vibration		Frequency 10 to 55 Hz, half amplitude 0.75 mm, for 10 cycles in 3 axial directions.				① No electrical discontinuity of 1 μs.			×	-	
Shock		981 m/s ² , duration of pulse 6 ms				② Contact resistance: 80 mΩ MAX(FPC) 100. mΩ MAX(FFC)				×	—
		at 3 times	s in 3 both axial directions.			No damage, crack and looseness of parts.					
Mechanical operation		10 times insertions and extractions.				① Contact resistance: 80 mΩ MAX(FPC) 100. mΩ MAX(FFC)			×	-	
FPC/FFC		Measure	Measured by applicable FPC/FFC.			② No damage, crack and looseness of parts. Insertion force: Direction of insertion			×	+_	
insertion/extraction force					(n : Number of contacts) 2+0.35×n N MAX (FPC/FFC) (<i>note 2</i>) 2+0.41×n N MAX (Shielded FFC) (<i>note 2</i>) Extraction force : Direction of extraction (n : Number of contacts) 4+0.32×n N MAX (FPC/FFC) (<i>note 2</i>) 4+0.42×n N MAX (Shielded FFC) (<i>note 2</i>)						
FPC/FFC		Measured by applicable FPC/FFC.			Direction of extraction				×	+_	
retention force		(Thickness of FPC/FFC shall be t=0.33mm at initial condition.)			(n : Number of contacts) 18+0.08×n N MIN (FPC/FFC) (note3) 15+0.1×n N MIN (Shielded FFC) (note3)						
ENVIRO	NMENTAL	CHARA	ACTERISTICS			101	0.121111		(Officiaca 1 1 0) (Notes)		
Rapid change of Tetemperature Ti		Temperature-55 \rightarrow +15To+35 \rightarrow +125 \rightarrow +15To+35°C Time 30 \rightarrow 2 to 3 \rightarrow 30 \rightarrow 2 to 3 min Under 1000 cycles.			① Contact resistance: 80 mΩ MAX(FPC) 100. mΩ MAX(FFC) ② Insulation resistance: 50 MΩ MIN.			×	_		
Damp heat (Steady state)		Exposed at 60±2 °C, Relative humidity 90 to 95 %, 96 h.			No damage, crack and looseness of parts.				×	-	
Damp heat,cyclic		Exposed at -10 to +65 °c, Relative humidity 90 to 96 %, 10 cycles, TOTAL 240 h.			 Contact resistance: 80 mΩ MAX(FPC) 100. mΩ MAX(FFC) Insulation resistance: 1 MΩ MIN. (At high humidity) Insulation resistance: 50 MΩ MIN. (At dry) 			×	-		
						No damage, crack and looseness of parts					
COUN 1	IT DE		ON OF REVISIONS		DESIG				CHECKED	DATE 20200615	
REMARK	N12-F		S-F-00006186		KN. KOBA	APPR		HS. HIRAHARA VED HH. SHINDO			80517
I NEW ALAN						CHECKE		ED	ED KN. SHIBUYA		80517
Unless atherwise specified ref			ofer to IFC 60512			DESIGNED			SI. TAMAKI		
Unless otherwise specified, refer to IEC 60512.				DRAWN DS. HIROWATARI				20180516			
Note QT:Qualification Test AT:Assurance Test X:Applicable Test SPECIFICATION SHEET HIROSE ELECTRIC CO., LTD.			Test		DRAWING NO. ELC-370364- PART NO. FH67-**\$-0.5\$\		ELC-370364-0	0-0	0		
					CODE NO					<u>A</u>	1/2
FORM HD0011					CODE	INU.			ULUUU	<u> </u>	1/2

	SPECIFICATION	ONS		
ITEM	TEST METHOD	REQUIREMENTS	QT	АТ
Dry heat	Exposed at 125±2°C, 1000 h.	① Contact resistance: 80 mΩ MAX(FPC)	×	_
Cold	Exposed at -55±3°C, 1000 h.	100. mΩ MAX(FFC)	×	_
	,	② No damage, crack and looseness of parts		
Sulphur dioxide	Exposed at 40±2 °C,	① Contact resistance: 80 mΩ MAX(FPC)	×	
[JIS C 60068-2-42	Relative humidity 80±5%	100. mΩ MAX(FFC)		
	25 ± 5 ppm for 96 h.			
Solderability	Soldered at solder temperature,	A new uniform coating of solder shall cover a	×	_
	245±0.3°C for immersion duration,3±0.3 sec.	minimum of 95 % of the surface being		
		immersed.		
Resistance to	1) Reflow soldering :	No deformation of case of excessive	×	_
soldering heat	Peak TMP. 250 °C MAX .	looseness of the terminals. (note 4)		
	Reflow TMP. over 220 °C 60 to 90 sec.			
	Number of reflow : 2 times			
	2) Soldering irons :			
	TMP. 350 ± 10 °C for 5 ± 1 sec .			

(note 1)

This product features "One Action Lock" and vertical mount.

"One Action Lock" completes FPC/FFC lock just by inserting the FPC/FFC.

Do not operate the actuator when inserting the FPC/FFC.

(note 2)

Do not insert the FPC/FFC to this product at an angle.

(note 3)

Stabilize the FPC/FFC to PCB or something fixed, if pull-up or pull-down force is exepected to be applied to the FPC/FFC.

There's a case witch FPC/FFC retention force doesn't fulfill the value, because FPC/FFC specification affects the result of FPC/FFC retention force.

(note 4)

Blisters which may be generated on the housing do not affect product performance.

(note 5)

The occurrence and the length of whisker, and the performance deterioration caused by it are out of the scope of this specification



4 (note 6)

The heat resistant temperature when using FFC is 105°C.

When the heat resistant temperature of FPC/FFC is less than 125°C/105°C, the heat resistant temperature of FPC/FFC is applied.

Note QT:0	Qualification Test AT:Assurance Test X:Applicable Test	DRAWIN	NG NO.	ELC-370364-00-00		
HS	LRG SPECIFICATION SHEET			FH67-**S-0. 5SV		
1.0	HIROSE ELECTRIC CO., LTD.	CODE NO		CL580	A	2/2